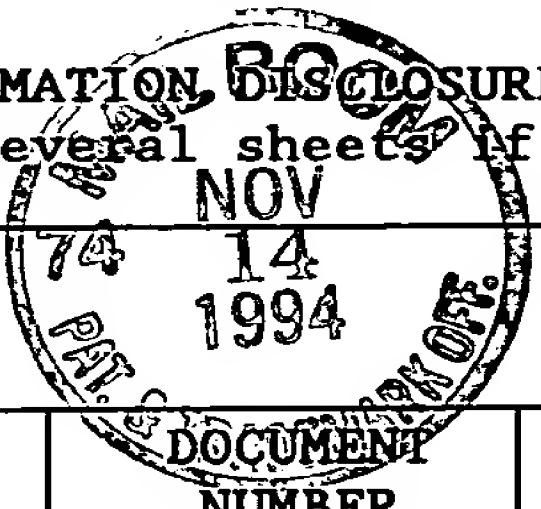


FORM PTO-1449 (REV. 7-80)	U.S. DEPARTMENT OF COMMERCE PATENT AND TRADEMARK OFFICE	ATTY. DOCKET NO. 26860/0033:37 USA	SERIAL NO. 08/276,797
INFORMATION DISCLOSURE CITATION (Use several sheets if necessary)		APPLICANT Mark D. Owen	
		FILING DATE July 18, 1994	GROUP <u>Unknown</u> 2106



U.S. PATENT DOCUMENTS

EXAMINER INITIAL		DOCUMENT NUMBER							DATE	NAME	CLASS	SUBCLASS	FILING DATE IF APPROPRIATE
Am	AA	5	1	5	3	4	0	8	10/06/92	Handford et al.	219	121.64	
Am	AB	4	9	1	5	9	8	1	04/10/90	Traskos et al.	427	53.1	
Am	AC	4	8	3	2	7	8	8	05/23/89	Nemiroff	156	643	
	AD												
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	AF												
	AG												
	AH												
	AI												
	AJ												
	AK												

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 JAN 28 1995
 GROUP 2500

FOREIGN PATENT DOCUMENTS

		DOCUMENT NUMBER							DATE	COUNTRY	CLASS	SUBCLASS	TRANSLATION YES NO	
	AL													
	AM													

OTHER DOCUMENTS (Including Author, Title, Date, Pertinent Pages, etc.)

<i>Am</i>	AN	Pete Singer, "The Interconnect Challenge: Filling Small, High Aspects Ratio Contact Holes," <i>Semiconductor International</i> , August 1994, pp. 57-64
<i>Am</i>	AO	"Printed Circuit Operations - A View from Inside," <i>Unisys</i>
<i>Am</i>	AP	Richard Harris et al., "MCM Micromachining: Nd:YAG UV Laser Process is a New Option," <i>Electro Scientific Industries, Inc.</i> , Spring 1993
<i>Am</i>	AQ	"LaserPulse," <i>Electro Scientific Industries, Inc.</i> , Fall 1993, pp. 1-7
<i>Am</i>	AR	Y.S. Liu, "Laser Metal Deposition for High-Density Interconnect," <i>Optics & Photonics News</i> , June 1992, pp. 10-14
<i>Am</i>	AS	Friedrich G. Bachmann, "Large scale industrial application for excimer-lasers; via-hole-drilling by photo-ablation," <i>SPIE</i> , Vol. 1361, Physical Concepts of Materials for Novel Optoelectronic Device Applications, 1990, pp. 500-511

EXAMINER <i>Gregory Mills</i>	DATE CONSIDERED <i>10-6-95</i>
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EXAMINER: Initial if reference considered, whether or not citation is in conformance with MPEP609. Draw line through citation if not in conformance and not considered. Include copy of this form with next communication to applicant. PATENT